ABBOCIATION CONNECTING ELECTRONICS INDUSTRIES® MAterial Composition D © Copyright 2005. IPC, Bannocl international and Pan-American	burn. Illinois. A	ll rights reserved un tions.	nder both	This docume evel parts, t	ent is a declaration en	n of the substar compasses all le	ces within the manufacture ower level materials for w	rer listed it hich the m	em. Note: if anufacturer	the item is an as the engineering	sembly with lower responsibility.	
			Form Type * Distribute	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information								
Supplier Information												
Company name* Company unique ID				Unique ID Authority				Response Date*				
onsemi	nsemi								2025-06-07			
Contact Name	Title - Contact				Phone - Contact*				Email - Contact*			
roduct-Env-Stewards Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Authorized Representative* Title - Representative				Phone - Representative*				Email - Representative*				
Product-Env-Stewards Product Enviro Complia			Compliance		NA			Product-Env-Stewards@onsemi.com				
Requester Item Number Mfr Ite	n Number	Mfr Item Name			Effective Date	Version	Manufacturing Site		Weight*	UOM	Unit Type	
BAV70	V70DXV6T5G SS SOT563 SWITCH		CH DIODE		2025-06-07		CN1	2	2.72	mg	Each	
Manufacturing Proccess Information		·			·							
Terminal Plating / Grid Array Material	Terminal Base Alloy J-ST		-STD-020 MSL	Rating	Peak Process Body Temperature Max Ti		rature Max Time at Peak	Temperature Number of Reflow Cycles		eles		
Matte Tin (Sn) - annealed CU Alloy 1				260	С	30	secon	ds 3				
Comments												
evel 1 - maximum time at peak temperature during s	oldering is 10-3	0 seconds										
for more information regarding material composition	please refer to	page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed				
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		nium (Cr6+), Polybro	ominated Biphenyls (PBB), Polybron	dmium and quantity limit of 0.1% by mass (100 minated Diphenyl Ethers (PBDE), and Bis(2-eth					
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of				
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted				
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.									
Exemption List Version	EL-2011/534/EU								
Declaration Signature									
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the				
Supplier Digital Signature Ra	stislav Drska	Le							

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3

sigma range of distribution unless otherwise noted).									
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure	
Die	0.06	mg	Supplier	Silicon (Si)	7440-21-3		0.06	mg	
Lead Frame	1.18	mg	Supplier	Silver (Ag)	7440-22-4		0.21	mg	
			В	Nickel (Ni)	7440-02-0		0.3646	mg	
			Supplier	Iron (Fe)	7439-89-6		0.5039	mg	
			Supplier	Copper (Cu)	7440-50-8		0.1015	mg	
Mold Compound-Black	1.4	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.14	mg	
			Supplier	Carbon Black (C)	1333-86-4		0.007	mg	
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		0.203	mg	
			Supplier	Fused Silica (SiO2)	60676-86-0		0.91	mg	
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.14	mg	
Plating	0.06	mg	Supplier	Tin (Sn)	7440-31-5		0.06	mg	
Wire Bond - Cu	0.02	mg	Supplier	Copper (Cu)	7440-50-8		0.02	mg	